

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10538306			
<b>Filing Date:</b>	09-Jun-2005			
<b>Title of Invention:</b>	Copper alloy for wiring, semiconductor device, method for forming wiring and method for manufacturing semiconductor device			
<b>First Named Inventor/Applicant Name:</b>	Makoto Ueki			
<b>Filer:</b>	Bruce Elliot Kramer/Kelley Liphard			
<b>Attorney Docket Number:</b>	Q88465			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 2 months with \$0 paid	1252	1	450	450

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	790	790
<b>Total in USD (\$)</b>				<b>1240</b>